

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	(implant\$3 adj through) with ((polymer or plastic or paper or (flexible adj glass) or (stainless adj steel)) with substrate\$1)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/11 09:07
L2	467	(438/406).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/03/11 09:07
L3	1858	(438/455).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/03/11 09:07
L4	899	(257/E21.567).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/03/11 09:08
L5	0	(flexible adj substrate) and (single adj crystalline adj silicon adj substrate) and disposed adj adjacent and (bond\$3 adj between) and induced and (ion adj implantation adj process) and through and interface and plurality and (semiconductor adj device).clm.	US-PGPUB	OR	OFF	2009/03/11 09:08
S1	2	((("6858480") or ("20030013280")).PN.	US-PGPUB; USPAT	OR	OFF	2008/01/07 00:14
S2	143487	ion with implant\$5	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/07 00:14
S3	5632559	bond\$3 or attach\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/06 22:45

S4	7061	S2 same S3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/06 22:39
S5	85565	flexible with substrate\$1	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/06 22:03
S6	375325	silicon with substrate\$1	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/06 22:03
S7	5219	S5 same S6	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/06 22:03
S8	4	S4 same S7	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/06 22:05
S9	284542	(polymer or plastic or paper or (flexible adj glass) or (stainless adj steel)) with substrate\$1	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/06 22:07
S10	25457	S6 same S9	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/06 22:07
S11	27	S4 same S10	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/06 22:07
S12	143551	((ion with implant\$5) or ((mix\$3 with implant\$5) same interface)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/06 22:26

S13	7066	S12 same S3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/06 22:26
S14	27	S10 same S13	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/06 22:27
S15	0	S14 not S11	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/06 22:28
S16	71	S13 same S9	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/06 22:28
S17	54	S16 and S6	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/06 22:28
S18	2	("6555182").URPN.	USPAT	OR	OFF	2008/01/06 22:34
S19	8	("4028206").URPN.	USPAT	OR	OFF	2008/01/06 22:37
S20	9	("2761945" "3694337" "3793167" "3798146" "3826728").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/01/06 22:38
S21	3350	S2 with S3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/06 22:40
S22	655	(ion with implant\$5) near3 (bond\$3 or attach\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/06 22:41

S23	17	S22 and S7	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/06 22:41
S24	5968902	bond\$3 or attach\$3 or adhesion	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/06 22:45
S25	3795	S2 with S24	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/06 22:45
S26	63	S7 and S25	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/06 22:47
S27	1	adhesion same silicon same polymer same implant\$3 same (hydrogen adj ion\$1)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/06 23:19
S28	10	adhesion same silicon same polymer same implant\$3 same ion\$1	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/06 22:53
S29	743	adhesion same implant\$3 same ion\$1	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/06 22:56
S30	14	S29 same S9	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/06 22:55
S31	47	adhesion with (implant\$3 adj ion\$1)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/06 23:00

S32	8	S31 and S9	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/06 22:57
S33	39	S31 not S32	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/06 23:02
S34	1	S33 same polymer	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/06 23:02
S35	5	S33 and polymer	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/06 23:13
S36	1	("6143670").PN.	USPAT	OR	OFF	2008/01/06 23:13
S37	6	(bond\$3 or adhesion) same (polymer or (flexible adj substrate)) same (using adj implant\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/06 23:49
S38	78	(bond\$3 or adhesion) same (using adj implant \$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/06 23:30
S39	1	S38 same (hydrogen adj ion\$1)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/06 23:23
S40	14	S38 same ion\$1	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/06 23:23

S41	34	(bond\$3 or adhesion) with (using adj implant\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/06 23:30
S42	19	us\$3 with implant\$3 with (adhere with polymer)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/06 23:51
S43	4	implant\$5 with (adhere with (polymer adj substrate))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/07 00:07
S44	1	2006-646680.NRAN.	DERWENT	OR	OFF	2008/01/06 23:52
S45	415	(ion adj implant\$5) with adher\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/06 23:55
S46	20	S45 same (hydrogen adj ion\$1)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/06 23:56
S47	50	S26 and S9	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/06 23:58
S48	1	S46 and S9	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/06 23:56
S49	5	S45 same S9	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/06 23:56

S50	63	S26 and S5	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/06 23:58
S51	106	implant\$5 with adhere with polymer	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/07 00:15
S52	35	implant\$5 with adhere with polymer and silicon	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/07 00:09
S53	1	S1 and polymer	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/07 00:15
S54	1	S1 and (implant\$5 and polymer)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/07 00:15
S55	0	S1 and (implant\$5 same polymer)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/07 00:16
S56	1	S1 and (implant\$5 and polymer and adher\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/07 00:16
S57	2	((("6858480") or ("20030013280")).PN.	US-PGPUB; USPAT	OR	OFF	2008/03/30 03:45
S58	42913	bond\$3 with interface	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/01 12:43

S59	314133	(polymer or plastic or paper or (flexible adj glass) or (stainless adj steel)) with substrate\$1	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/01 12:44
S60	381	S58 with S59	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/01 12:46
S61	511879	"438"/\$.ccls. or "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/01 12:50
S62	45	S60 and S61	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/01 12:50
S63	8447	implant\$3 with bond\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/01 13:04
S64	1037	S59 and S63	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/01 13:05
S65	335	S61 and S64	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/01 13:05
S66	1	(implant\$3 adj through) with ((polymer or plastic or paper or (flexible adj glass) or (stainless adj steel)) with substrate\$1)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/01 13:27
S67	456	(438/406).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/12/01 13:31

S68	1807	(438/455).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/12/01 13:32
S69	850	(257/E21.567).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/12/01 14:25
S70	0	(flexible adj substrate) and (single adj crystalline adj silicon adj substrate) and disposed adj adjacent and (bond\$3 adj between) and induced and (ion adj implantation adj process) and through and interface and plurality and (semiconductor adj device).clm.	US-PGPUB	OR	OFF	2008/12/01 15:50
S71	1	(implant\$3 adj through) with ((polymer or plastic or paper or (flexible adj glass) or (stainless adj steel)) with substrate\$1)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/10 21:41

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